

Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	400	V_{P}
Reverse Input Voltage	5	V
Input Control Current	100	mA
Peak (10ms)	1	Α
Input Power Dissipation ¹	150	mW
P _{MAX} , Total Package Dissipation ²	1600	mW
Isolation Voltage, Input to Output	3750	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33 mW / °C 2 Derate linearly 16.6 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25°C

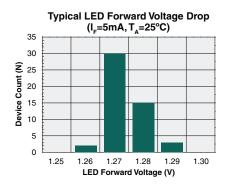
Parameters	Conditions	Symbol	Min	Тур	Max	Units	
Output Characteristics			-				
Operating Voltage Range	V _I	-	20	-	120	V_{rms}	
Load Current, Continuous	$V_L = 120 V_{rms}$	Ι _L	0.005	-	1	A _{rms}	
Non-Repetitive Single Cycle Surge Current	-	I _{TSM}	-	-	10	A	
Off State Leakage Current	$V_L = 400 V_P$	I _{LEAK}	-	-	1	mA	
On-State Voltage Drop	I _L =1A _{rms}	-	-	-	1.6	V _{rms}	
Critical Rate of Rise 3	-	dV/dt	1000	-	-	V/µs	
Switching Speeds							
Turn-on	Ι . Γ Λ	t _{on}	-	-	0.5	avelee.	
Turn-off	I _F =5 mA	t _{off}	-	-	0.5	0.5 cycles	
Zero-Cross Turn-On Voltage 1	1st half-cycle	-	-	2	10	V	
	Subsequent half-cycle	-	-	1	-	V	
Operating Frequency	-	-	20	-	400	Hz	
Load Power Factor for Guaranteed Turn-On ²	-	PF	0.25	-	-	-	
Input Characteristics							
Input Control Current to Activate 4	-	I _F	-	0.8	5	mA	
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.5	V	
Input Drop-out Voltage	-	-	0.8	-	-	V	
Reverse Input Current	V _R =5V	I _R	-	-	10	μΑ	
Common Characteristics		••		•			
Input to Output Capacitance	V _{IO} =0V, f=1MHz	C _{IO}	-	3	-	pF	

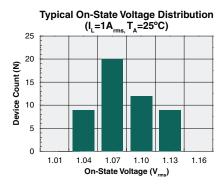
¹ Zero Cross 1st half-cycle @ <100Hz ² Snubber circuits may be required at low power factors. ³ Tested in accordance with EIA/NARM standard RS-443.

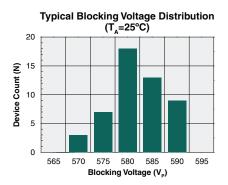
 $^{^4}$ For high noise environments, use I_F=10mA.

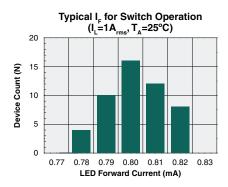


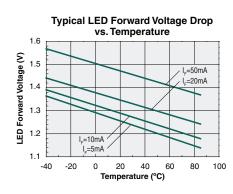
PERFORMANCE DATA*

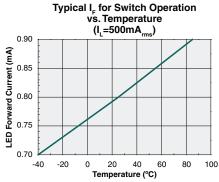


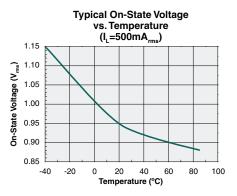








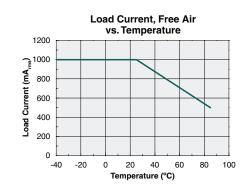


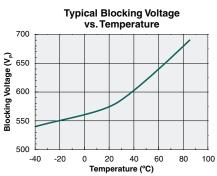


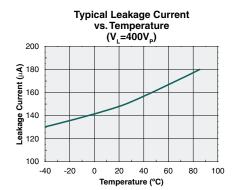
*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C. For guaranteed parameters not indicated in the written specifications, please contact our application department.

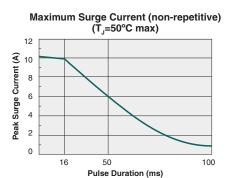


PERFORMANCE DATA*











Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
CPC1945Y	MSL 1

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Soldering Profile

Provided in the table below is the Classification Temperature (T_C) of this product and the maximum dwell time the body temperature of this device may be (T_C - 5)°C or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

Device	Classification Temperature (T _c)	Dwell Time (t _p)	Max Reflow Cycles
CPC1945Y	245°C	30 seconds	1

Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.



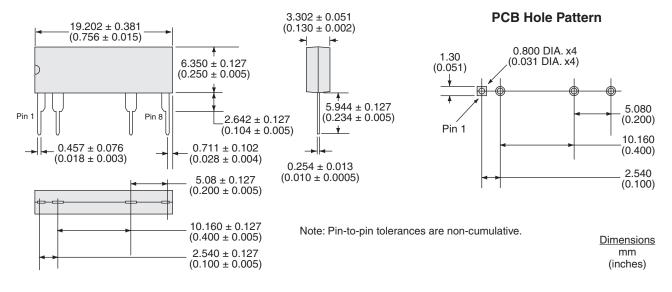






MECHANICAL DIMENSIONS

CPC1945Y



For additional information please visit our website at: www.ixysic.com

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